

# MSKSEMI

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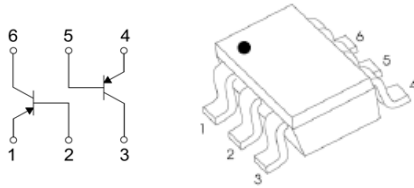
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PLED

Product data sheet

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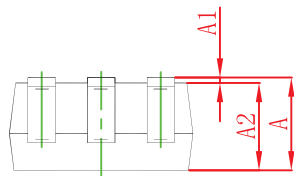
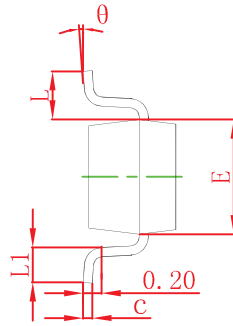
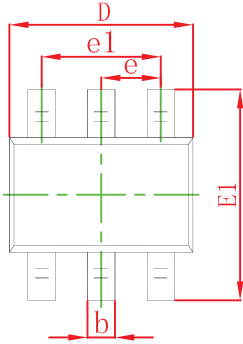

**SOT-363**
**MARKING:K3N**
**MAXIMUM RATINGS(T<sub>a</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Value	Units
V <sub>CBO</sub>	Collector-Base Voltage	-40	V
V <sub>CEO</sub>	Collector-Emitter Voltage	-40	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
I <sub>C</sub>	Collector Current -Continuous	-0.2	A
P <sub>C</sub>	Collector Power Dissipation	0.2	W
R <sub>θJA</sub>	Thermal Resistance. Junction to Ambient Air	625	°C/W
T <sub>J</sub>	Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature	-55-150	°C

**ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise specified)**

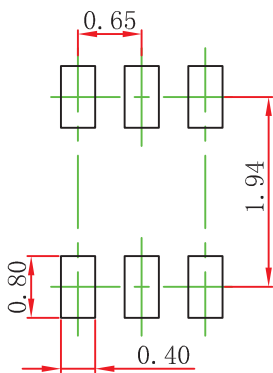
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-10μA, I <sub>E</sub> =0	-40			V
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> =-1mA, I <sub>B</sub> =0	-40			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =-10μA, I <sub>C</sub> =0	-5			V
Collector cut-off current	I <sub>CEX</sub>	V <sub>CE</sub> =-30V, V <sub>EB(OFF)</sub> =-3V			-50	nA
Base cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =-5V, I <sub>C</sub> =0			-50	nA
DC current gain	h <sub>FE(1)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-0.1mA	60			
	h <sub>FE(2)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-1mA	80			
	h <sub>FE(3)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-10mA	100		300	
	h <sub>FE(4)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-50mA	60			
	h <sub>FE(5)</sub>	V <sub>CE</sub> =-1V, I <sub>C</sub> =-100mA	30			
Collector-emitter saturation voltage	V <sub>CE(sat)1</sub>	I <sub>C</sub> =-10mA, I <sub>B</sub> =-1mA			-0.25	V
	V <sub>CE(sat)2</sub>	I <sub>C</sub> =-50mA, I <sub>B</sub> =-5mA			-0.4	V
Base-emitter saturation voltage	V <sub>BE(sat)1</sub>	I <sub>C</sub> =-10mA, I <sub>B</sub> =-1mA	-0.65		-0.85	V
	V <sub>BE(sat)2</sub>	I <sub>C</sub> =-50mA, I <sub>B</sub> =-5mA			-0.95	V
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> =-20V, I <sub>C</sub> =-10mA, f=100MHz	250			MHz
Collector output capacitance	C <sub>ob</sub>	V <sub>CB</sub> =-5V, I <sub>E</sub> =0, f=1MHz			4.5	pF
Noise figure	NF	V <sub>CE</sub> =-5V, I <sub>C</sub> =-0.1mA, f=1KHz, R <sub>g</sub> =1KΩ			4	dB
Delay time	t <sub>d</sub>	V <sub>CC</sub> =-3V, V <sub>BE</sub> =0.5V			35	nS
Rise time	t <sub>r</sub>	I <sub>C</sub> =-10mA, I <sub>B1</sub> =-I <sub>B2</sub> =-1mA			35	nS
Storage time	t <sub>s</sub>	V <sub>CC</sub> =-3V, I <sub>C</sub> =-10mA			225	nS
Fall time	t <sub>f</sub>	I <sub>B1</sub> =-I <sub>B2</sub> =-1mA			75	nS

**SOT-363 Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

**SOT-363 Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
MMDT3906	SOT-363	3000

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